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(12) **United States Design Patent**  
**Lee et al.**

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- (54) **SEMICONDUCTOR DEVICE**
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- (73) Assignee: **DONG WOON ANATECH CO., LTD**, Seoul (KR)
- (\*\*) Term: **15 Years**

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- (21) Appl. No.: **29/772,126**
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- (30) **Foreign Application Priority Data**  
Feb. 23, 2021 (KR) ..... 30-2021-0008923

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(Continued)

- (51) **LOC (13) Cl.** ..... **13-03**
- (52) **U.S. Cl.**  
USPC ..... **D13/182**
- (58) **Field of Classification Search**  
USPC ..... D13/101, 110, 112, 118, 120, 123, 133,  
D13/146, 147, 159, 154, 156, 174, 182,  
D13/184, 199; D14/356, 433, 435, 438  
CPC ..... H01R 24/00; H01R 12/00; H01R 12/70;  
H01R 13/62  
See application file for complete search history.

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(57) **CLAIM**

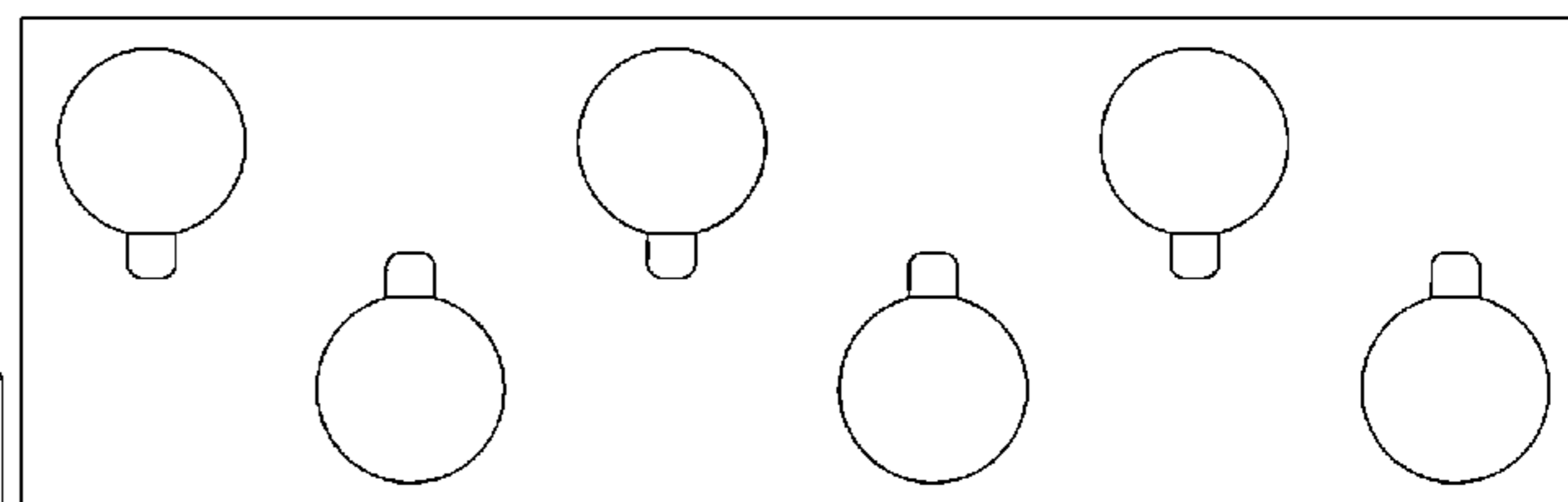
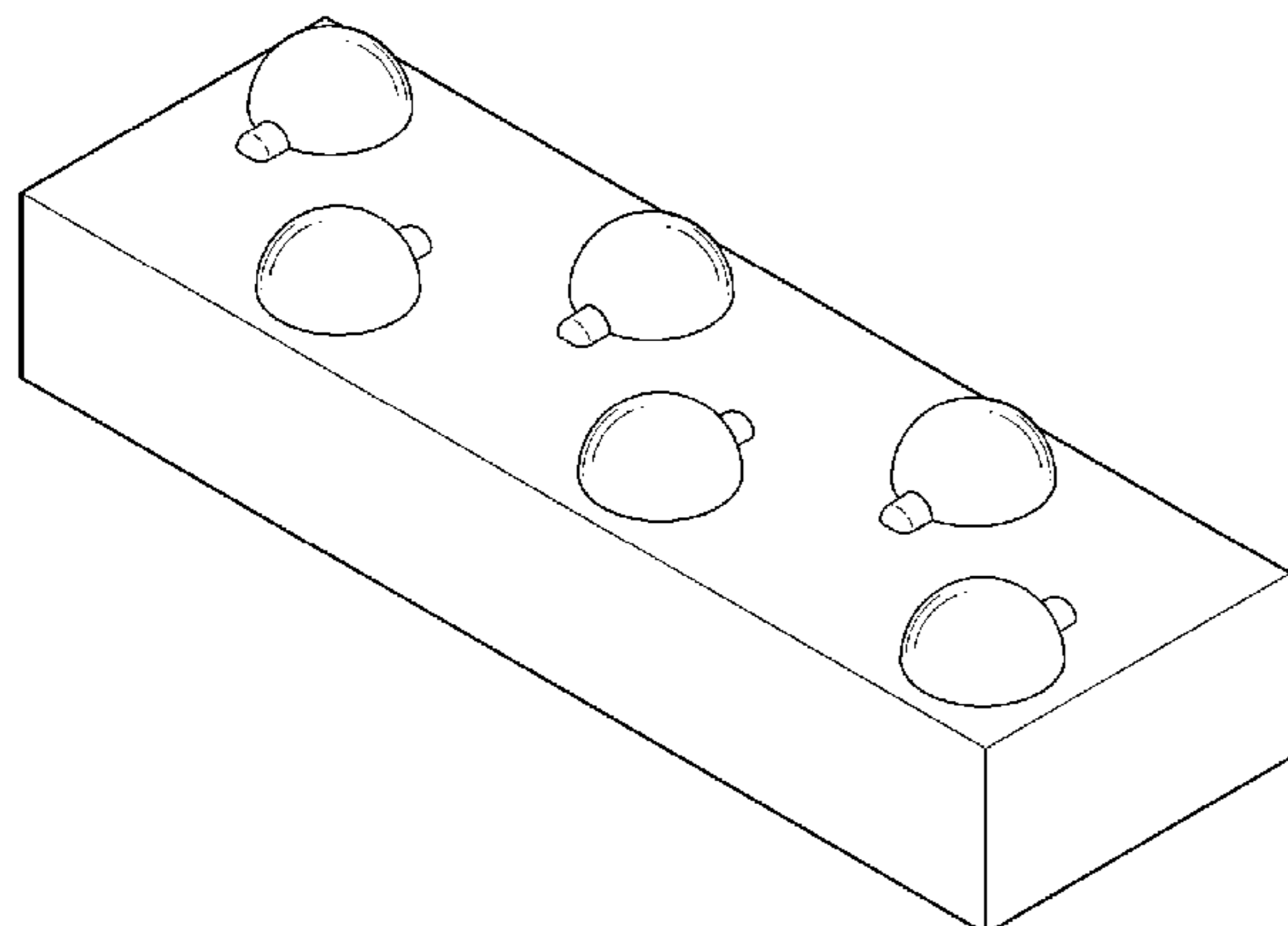
The ornamental design for a semiconductor device, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top, and right-side perspective view of a semiconductor device showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a back view thereof;  
FIG. 4 is a left-side view thereof;  
FIG. 5 is a right-side view thereof;  
FIG. 6 is a top view thereof; and,  
FIG. 7 is a bottom view thereof.

**1 Claim, 2 Drawing Sheets**

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FIG. 1

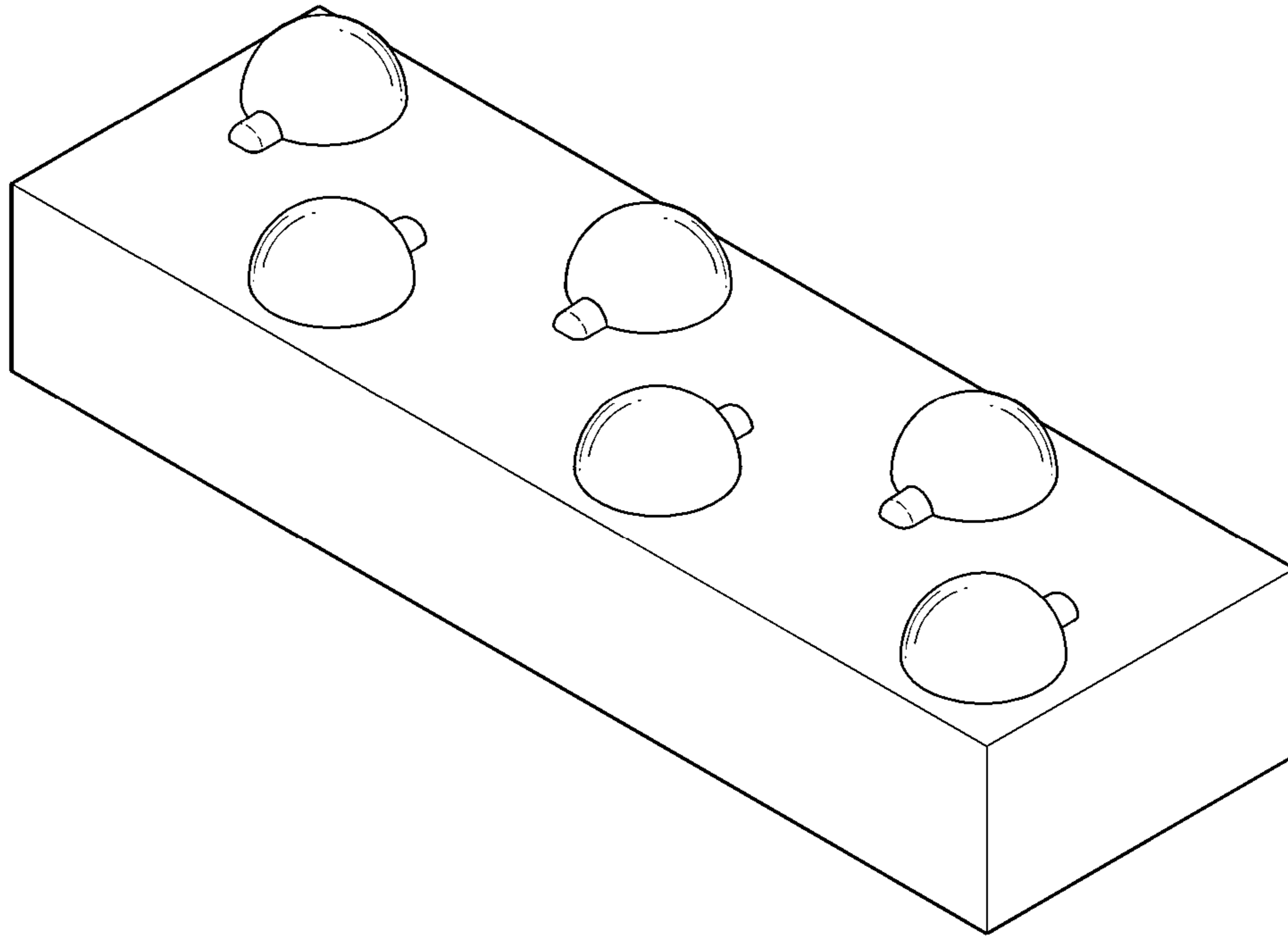


FIG. 2

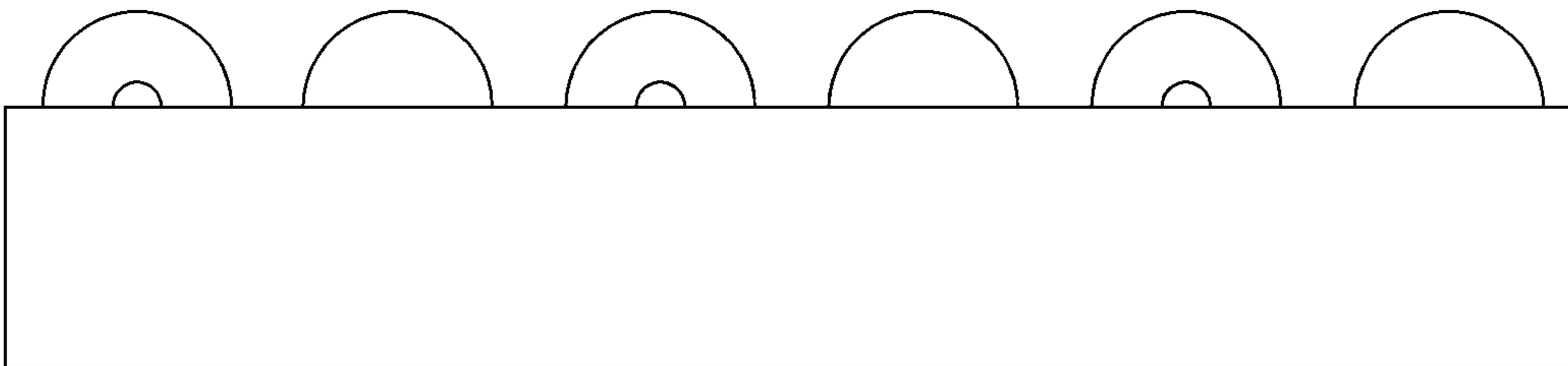


FIG. 3

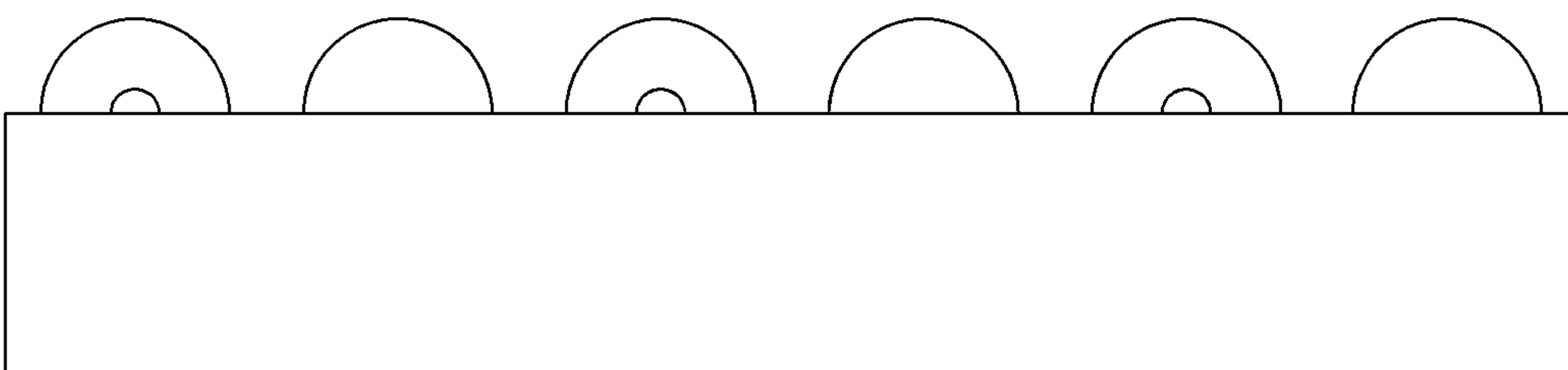


FIG. 4

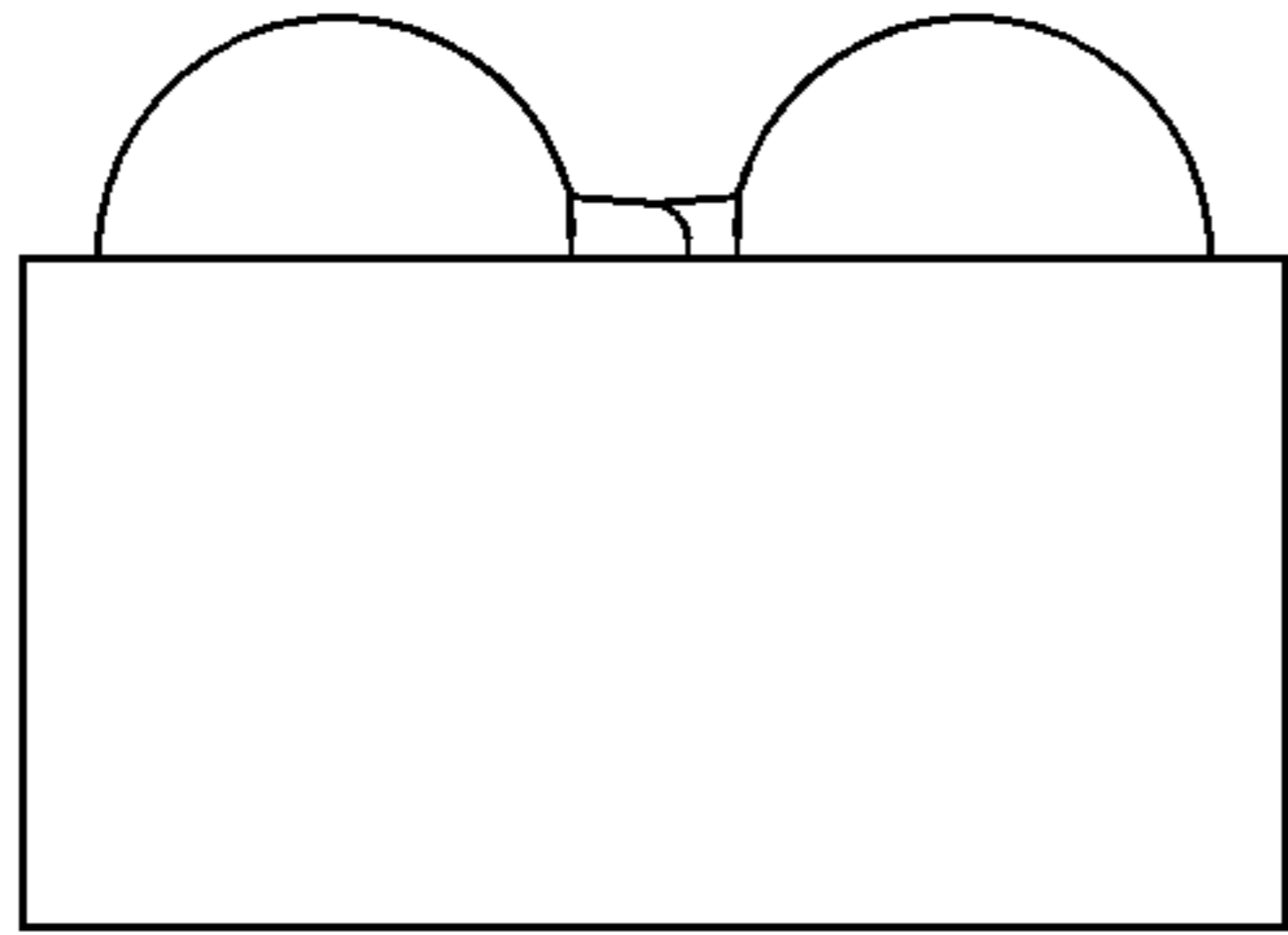


FIG. 5

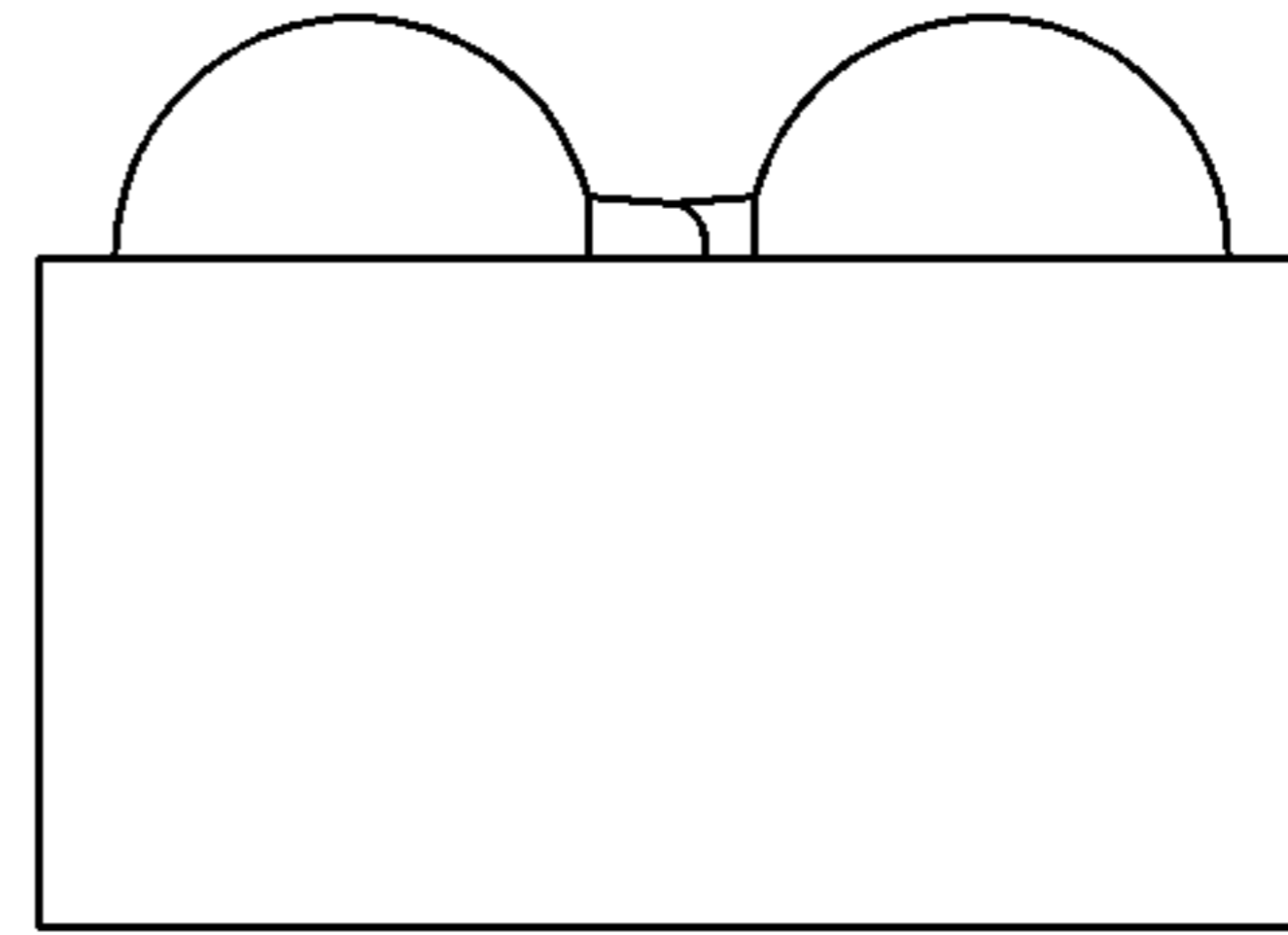


FIG. 6

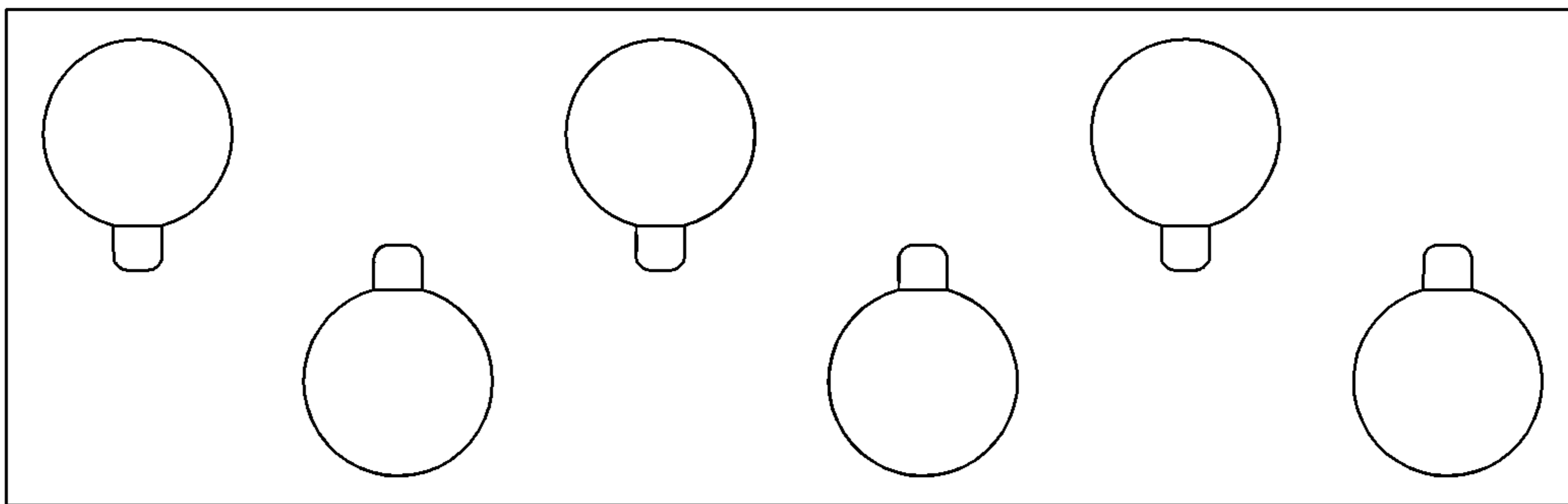


FIG. 7

